DOPES

(DIAGNOSTICS OF POWER ELECTRONIC SYSTEMS)

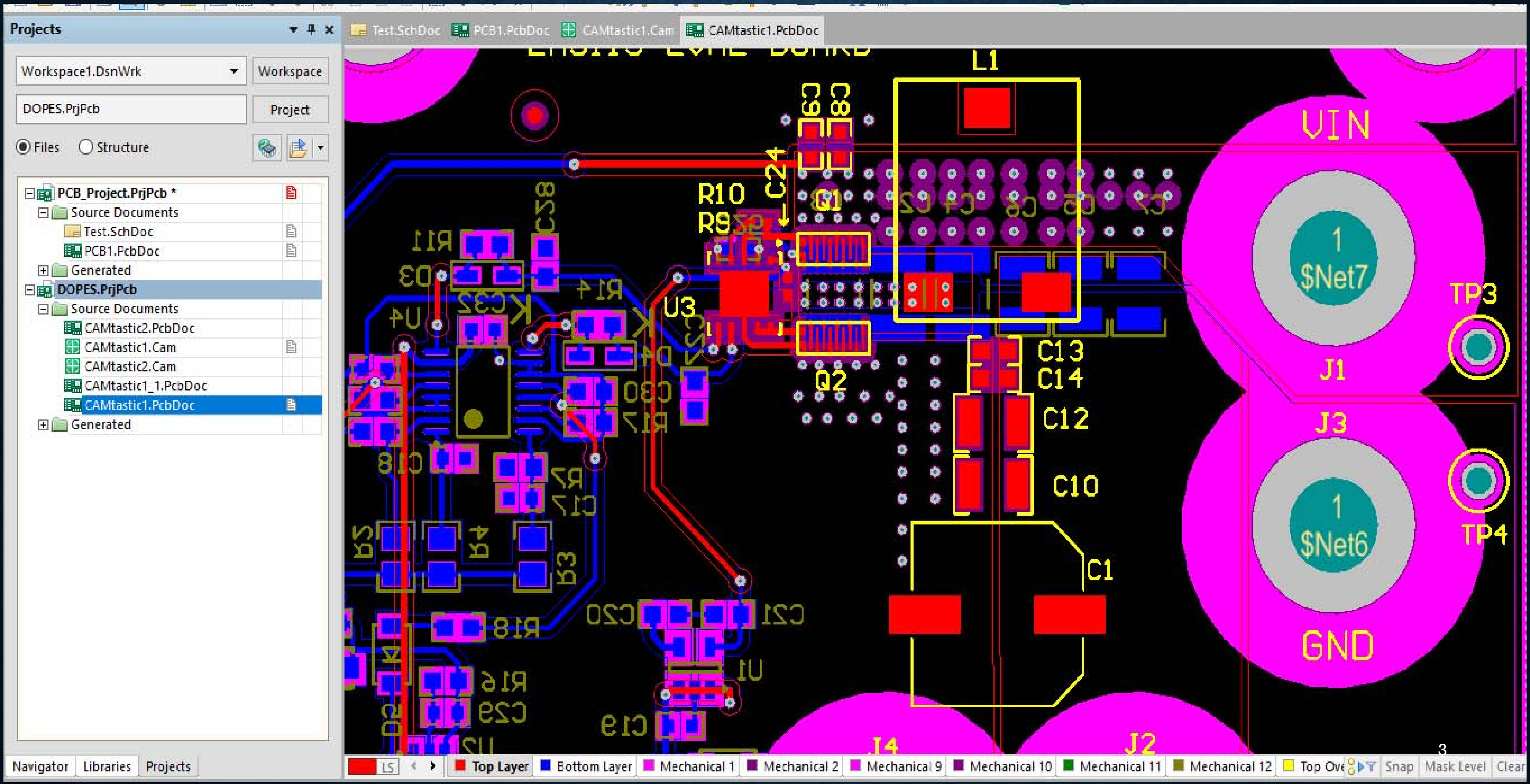
Progress Report 1

2/13/2018

Shamar Christian

MILESTONE SUMMARY

Month	Deliverable	Responsibility	Update
January – mid February	PCB Design Submission	Shamar Christian	Awaiting Status Update on manufacturing process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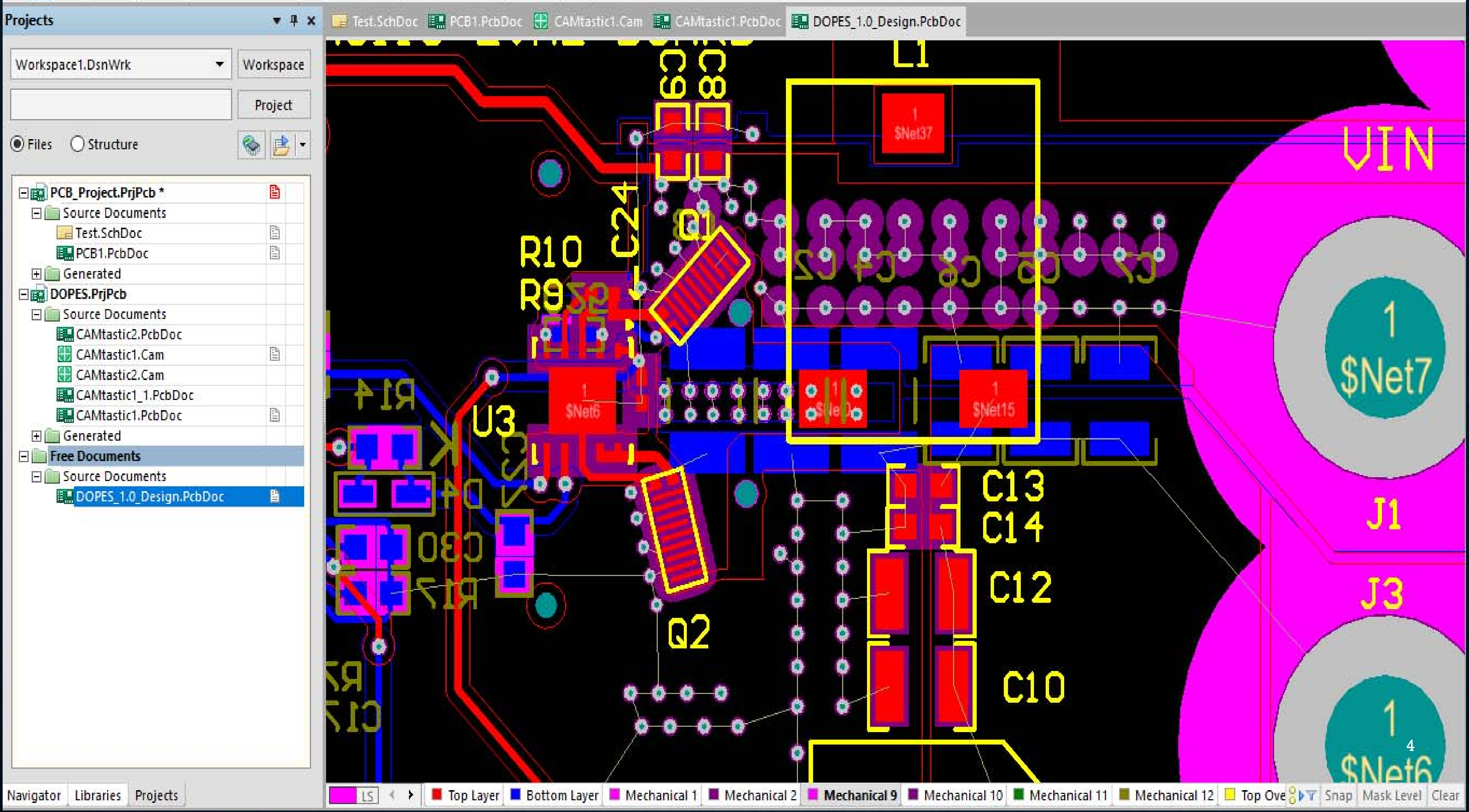
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ACTIVITY SUMMARY

Highlights

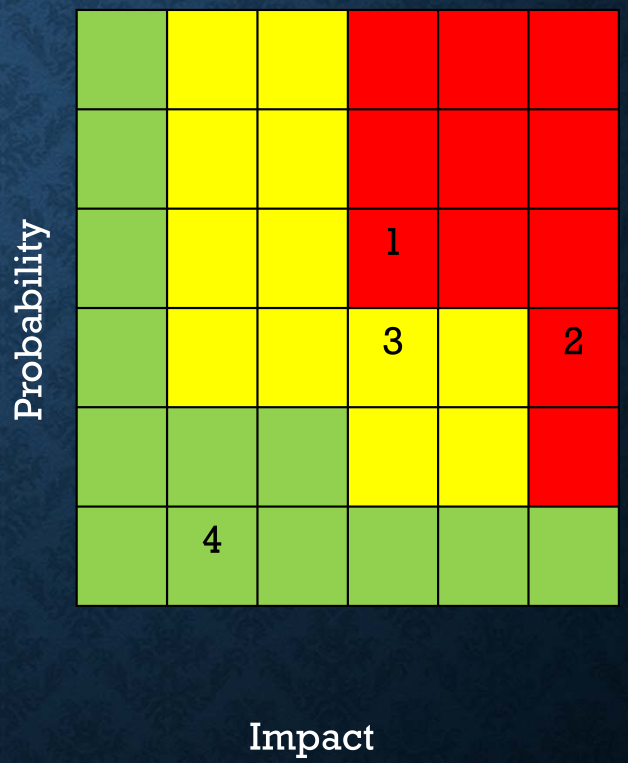
- Completed Circuit Redesign
- Successfully sent design to PCB mill
- Progress made in data analysis towards failure “definition”

Lowlights

- Waiting for new PCB to arrive
- Research into mitigation techniques depending on PCB mill instructions on redesign (if needed)
- No verification method

RISK MANAGEMENT

Rank	Risk	Approach
1	Incorrrect Copper Pour in Design	Redesign Copper Pour
2	Altered Circuit functionality	Simulate and modify design
3	Insufficient Data transported for PCB fabrication	Send entirety of exportation files to PCB mill
4	Low accuracy data yield	Modify Sensor z position



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PLANNED ACTIVITY FOR NEXT PERIOD

- Anticipated feedback of circuit redesign
- Assistance in further data processing
- LabView set up and manipulation for impedance spectroscopy
- Full implementation of redesigned circuit in current experimental setup